



# Fast and highly accurate in-situ calibration of AlGaAs ternary composition for MOVPE-based growth of edge-emitting diode lasers

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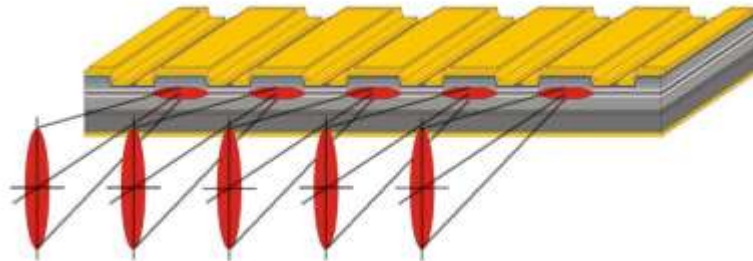
Oliver Schulz, J.-Thomas Zettler, LayTec, Berlin, Germany



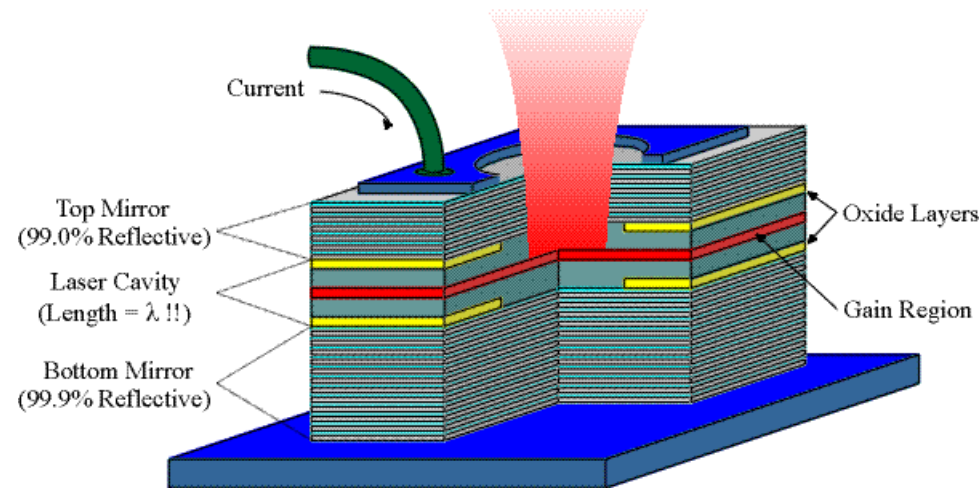
Anthony J. SpringThorpe, NRC of Canada, CPFC, Ottawa, Canada



# Introduction: manufacturing challenges for MOVPE of semiconductor laser diodes



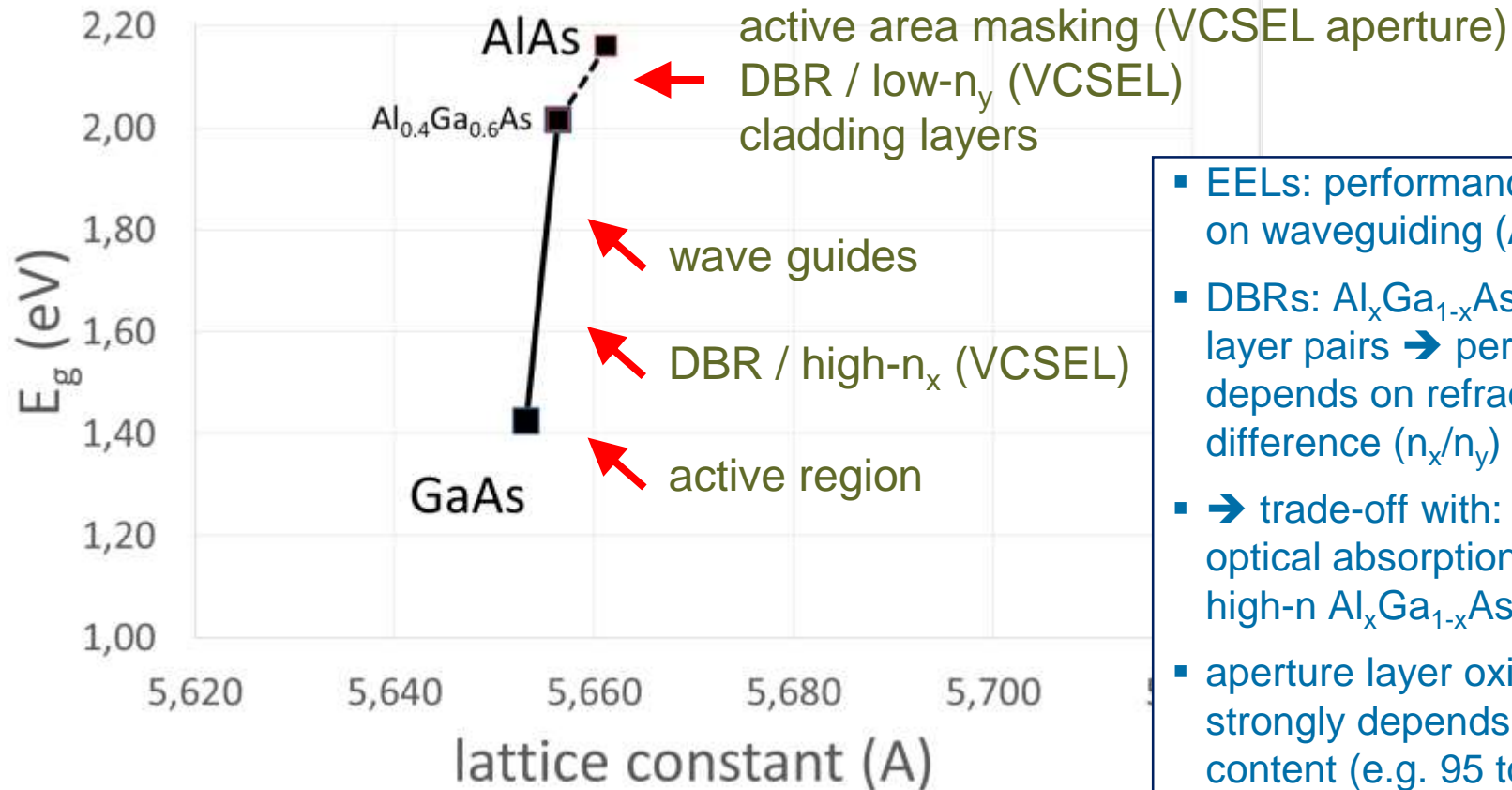
*laser bar (edge emitting laser diodes, EEL)*



*surface emitting laser (VCSEL)*

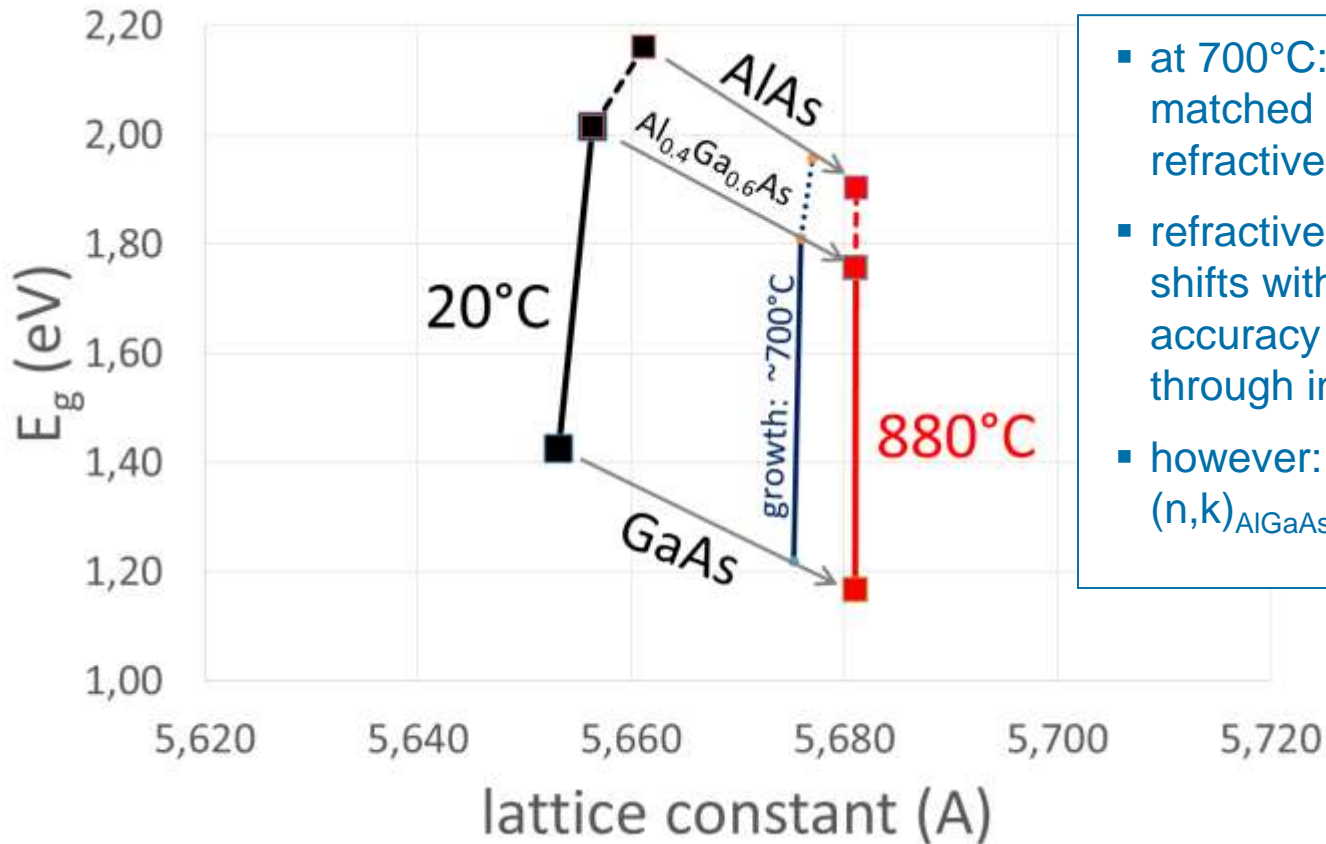
## Manufacturing of AlGaAs based lasers:

- stringent specifications: e.g. emission wavelength of final laser device  $\pm 1\text{nm}$
- Properties of waveguiding layers (AlGaAs) crucially defines device performance
- homogeneity and reproducibility of growth process  $\rightarrow$  high yield!



- EELs: performance depends on waveguiding (AlGaAs)
- DBRs:  $\text{Al}_x\text{Ga}_{1-x}\text{As}/\text{Al}_y\text{Ga}_{1-y}\text{As}$  layer pairs → performance depends on refractive index difference ( $n_x/n_y$ )
- → trade-off with: low DBR optical absorption (exact x in high-n  $\text{Al}_x\text{Ga}_{1-x}\text{As}$  !)
- aperture layer oxidation rate strongly depends on Al content (e.g. 95 to 98%)

→ AlGaAs composition with  $\pm 0.5\%$  accuracy needed !



- at  $700^\circ\text{C}$ : AlAs is  $\sim$ perfectly lattice matched  $\rightarrow$  no strain effects to in-situ refractive index  $n, k$  of AlGaAs
- refractive index  $n$ , similarly to  $E_g$ , shifts with  $x$   $\rightarrow$  promising high accuracy composition measurement through in-situ reflectance
- however: non-linear change of  $(n, k)_{\text{AlGaAs}}$  with wafer temperature!

**Target:** wafer temperature ( $\pm 1\text{K}$ ); in-situ  $n, k_{\text{AlGaAs}}$  ( $\pm 0.002$ )  
 $\rightarrow$  in-situ AlGaAs composition with accuracy ( $\pm 0.5\%$ )

1. MOCVD calibration runs with optimized stack structure and accurate  $T_{\text{wafer}}$
2. Ex-situ X-Ray diffraction (XRD) analysis → composition  $x$  and growth rate  $r$
3. Self-consistent analysis of in-situ data →  $nk(x,T)$  database referenced to XRD
4. Replacing time-consuming ex-situ calibration by fast, accurate and fully automated in-situ reflectance

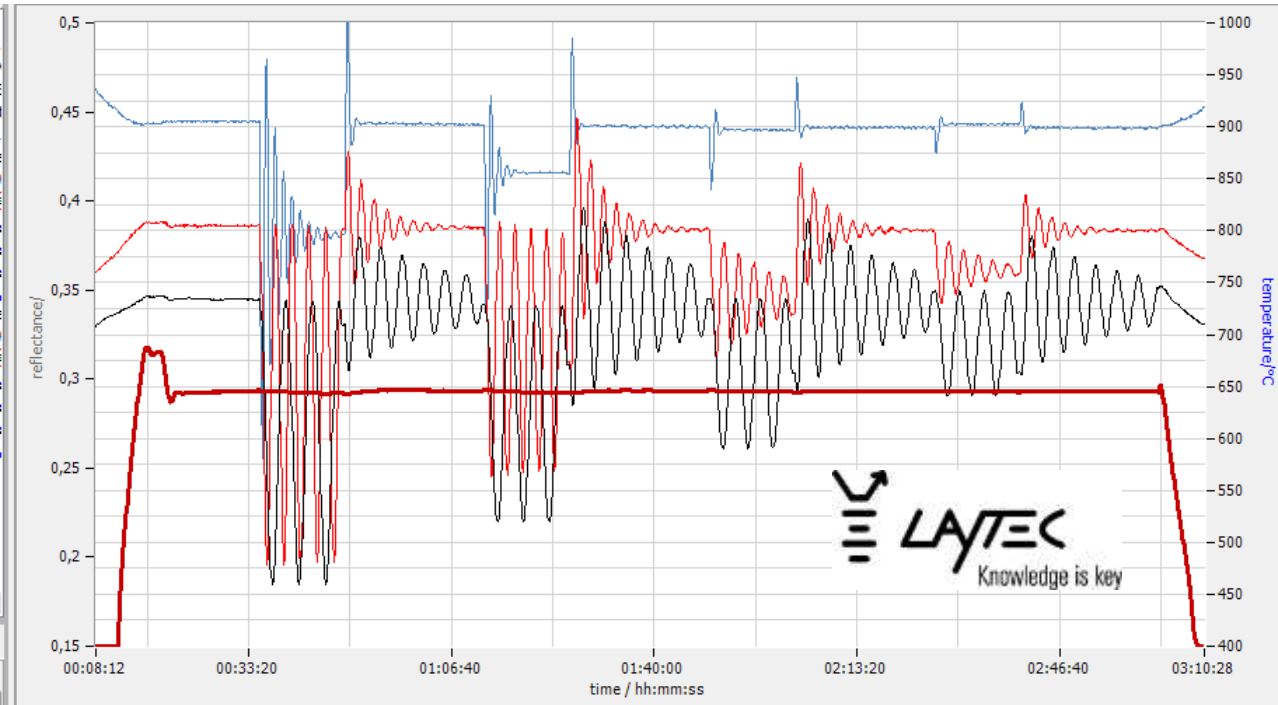
## Summary & Outlook

# Calibration runs for growing XRD test structures



- growth performed in production scale MOVPE (12x4")
- every AlGaAs layer is sandwiched between GaAs
- thick GaAs interlayers! → 633nm FPOs damped out
- 3 wavelength reflectance (633/405/950nm) + wafer temp.

Run A	Target	
Layer	Thickness	x
GaAs	750	0
Al(0,3)GaAs	450	0,3
GaAs	750	0
Al(0,5)GaAs	450	0,5
GaAs	750	0
Al(0,8)GaAs	450	0,8
GaAs	750	0
AlAs	450	1
GaAs-Sub.		0

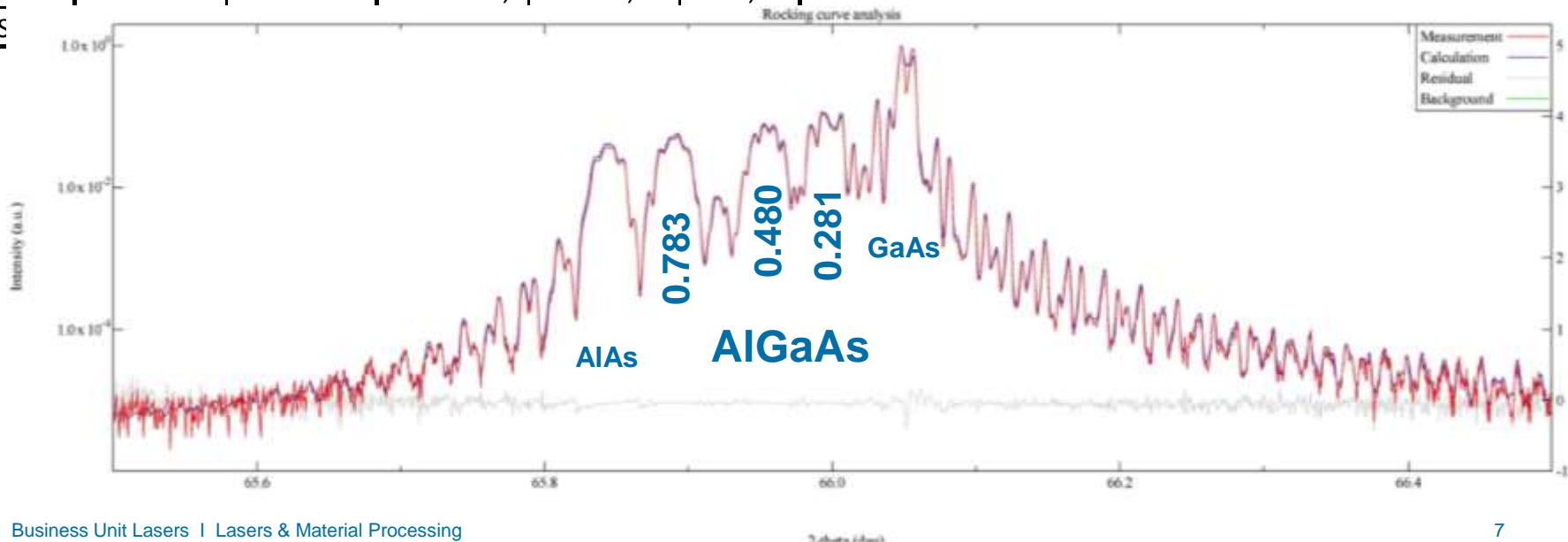


# Ex-situ XRD analysis of composition x and growth rate r

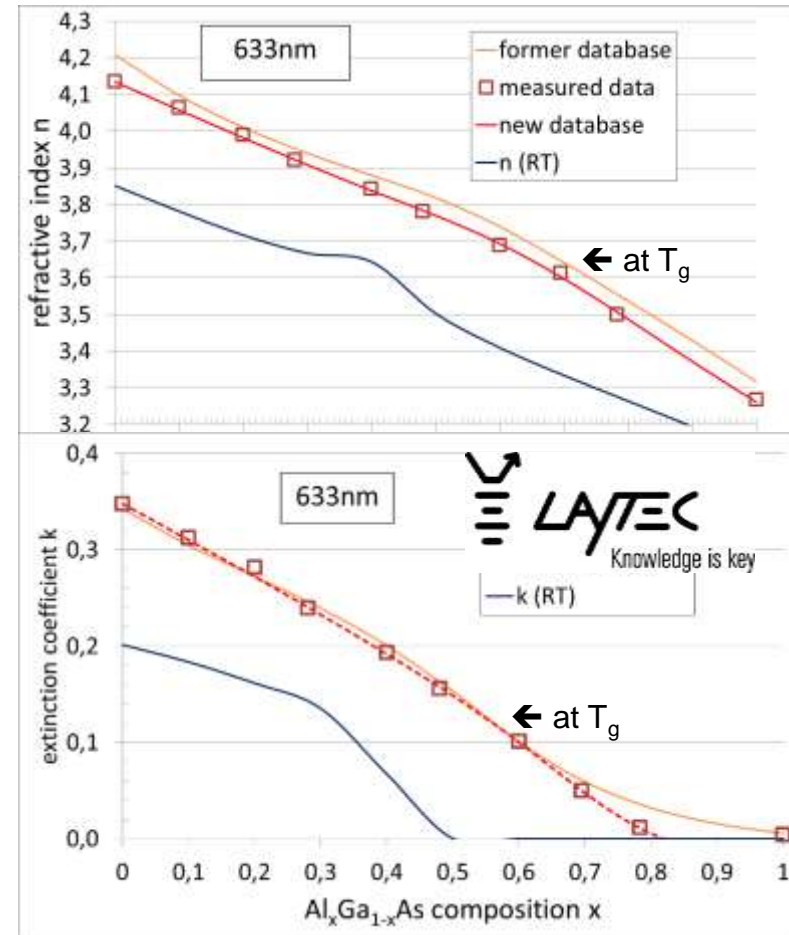


Run A					
	Target		XRD		
Layer	Thickness	x	Thickness	Rate (nm/s)	x
GaAs	750	0	806,1	<b>0,597</b>	0,000
Al(0,3)GaAs	450	0,3	448,9	0,553	0,281
GaAs	750	0	805,2	<b>0,596</b>	0,000
Al(0,5)GaAs	450	0,5	458,4	0,566	0,480
GaAs	750	0	804,4	<b>0,596</b>	0,000
Al(0,8)GaAs	450	0,8	472,1	0,583	0,783
GaAs	750	0	805,5	<b>0,597</b>	0,000
AlAs	450	1	477,1	0,589	1,000
GaAs-S					

- reference layer stack compositions by ex-situ rocking curve analysis (XRD)
- fine structure of rocking curve fitted for layer thickness measurement
- ➔ growth rates known from ex-situ XRD
- ➔ post-growth analysis of in-situ reflectance
- ➔ assigning  $x(\text{XRD})$  to  $nk_{\text{AlGaAs}}$  (in-situ)

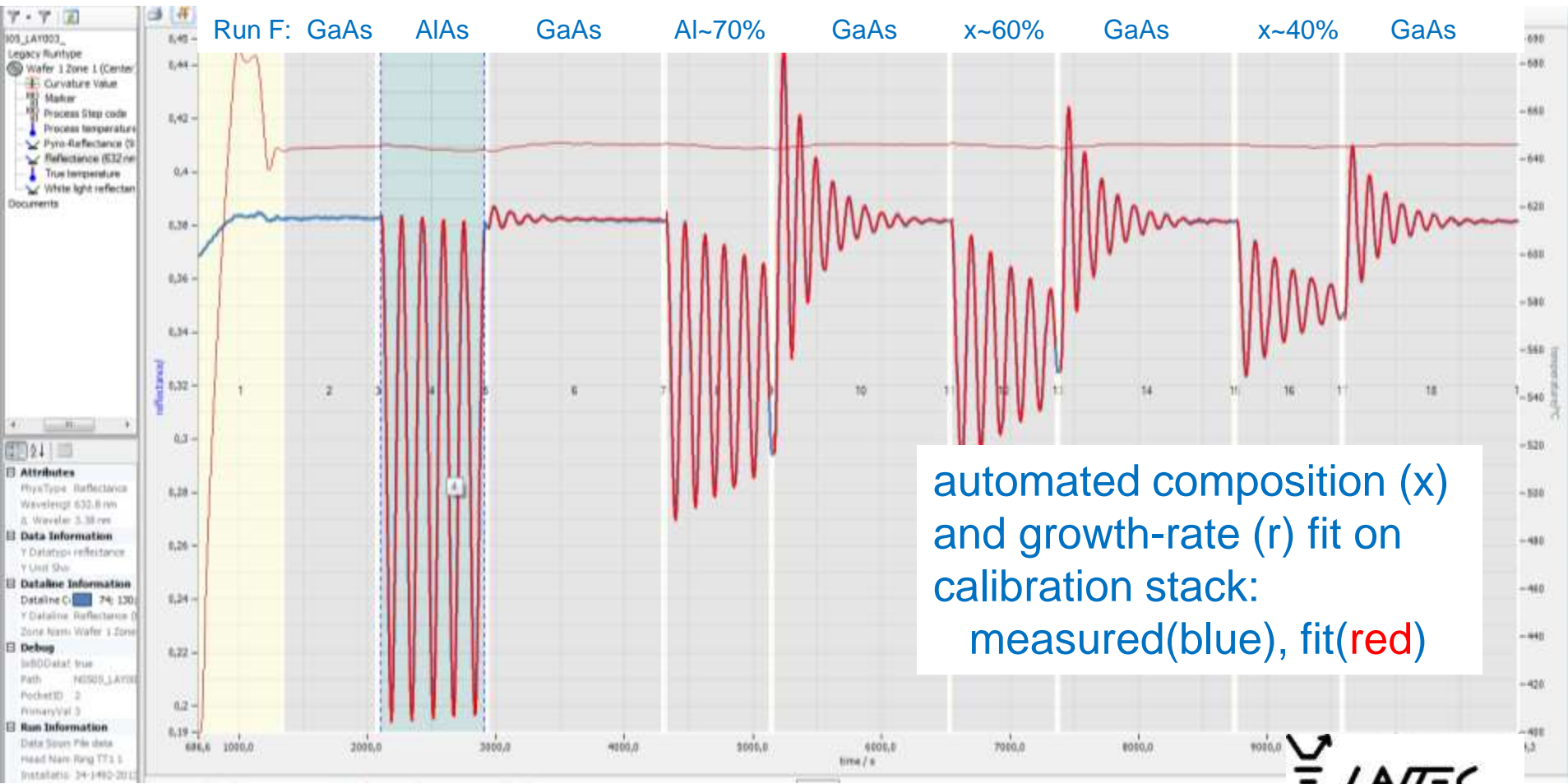


- With known XRD growth rates n and k have been determined by FPO analysis with an accuracy of  $\pm 0.002$  (for 633nm) in the full  $x=0\dots 100\%$  composition range and in the full  $600^\circ\text{C}\dots 710^\circ\text{C}$  surface temperature range
- emissivity corrected 950nm pyrometry in conjunction with handheld calibration radiation source (AbsoluT)  $\rightarrow$  wafer temperature  $T_g$  is exactly assigned





# Routine AlGaAs process calibration by in-situ reflectance



automated composition (x)  
and growth-rate (r) fit on  
calibration stack:  
measured(blue), fit(red)



Run F	Target		ex-situ XRD		in-situ	in-situ	in-situ	in-situ
Layer	d (nm)	x	r (nm/s)	x	r(nm/s)	x	$\Delta r/r$	$\Delta x$
GaAs	750	0,000	0,5971	0,000	0,602	0,002	0,8%	0,2%
Al(0,4)GaAs	450	0,400	0,5531	0,402	0,564	0,402	2,0%	0,0%
GaAs	750	0,000	0,5964	0,000	0,602	0,000	0,9%	0,0%
Al(0,6)GaAs	450	0,600	0,5659	0,601	0,558	0,607	-1,4%	0,6%
GaAs	750	0,000	0,5959	0,000	0,600	0,000	0,7%	0,0%
Al(0,7)GaAs	450	0,700	0,5828	0,695	0,577	0,690	-1,0%	-0,5%
GaAs	750	0,000	0,5967	0,000	0,599	0,000	0,4%	0,0%
AlAs	450	1,000	0,5890	1,000	0,598	1,000	1,5%	0,0%
GaAs-Sub.		0,000						

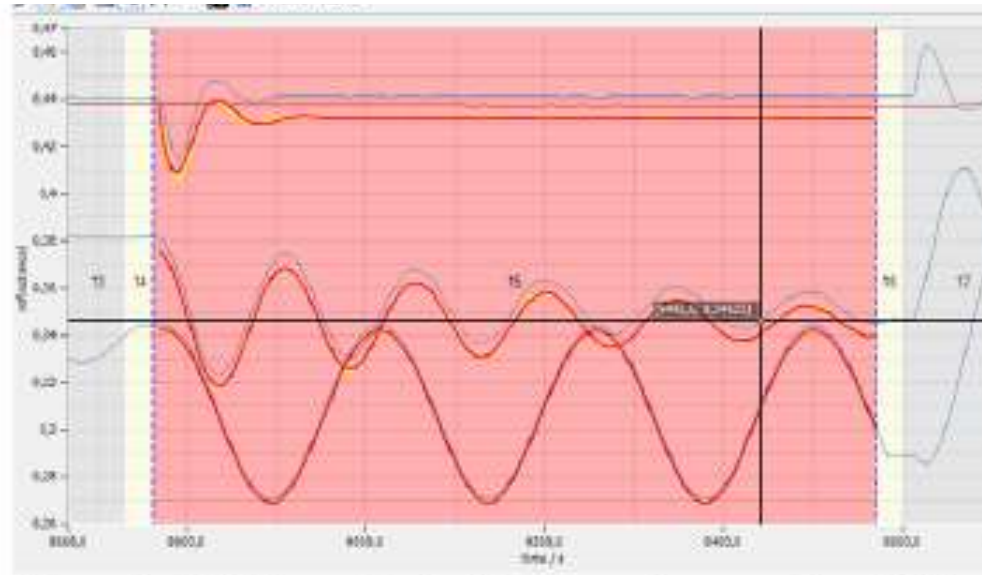
Single wavelength (633nm) in-situ reflectance analysis gives:

- AlGaAs composition with accuracy of  $\pm 0.5\%$
- growth rates with  $\pm 1\%$  variation from XRD

# Routine AlGaAs process calibration by in-situ reflectance



Run F: GaAs | | AlGaAs (x~40%) | | GaAs



Using all 3 wavelength for combined (633/405/950nm) in-situ reflectance analysis of growth rates / layer thickness gives:

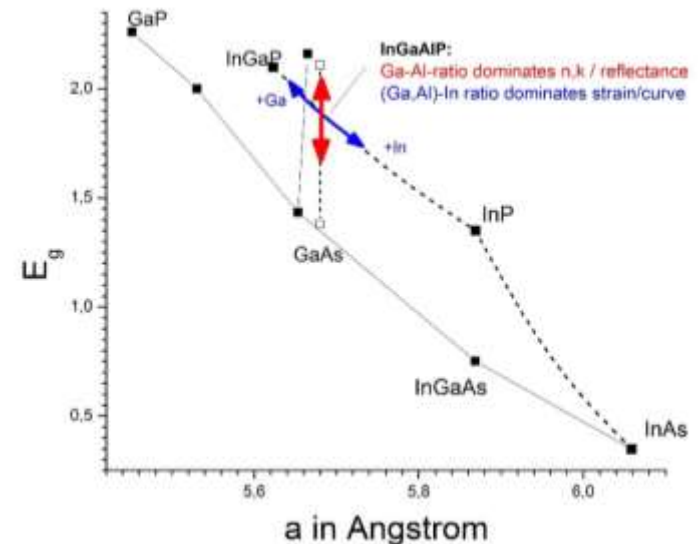
- In-situ growth rates with even better ( $\pm 0.3\%$ ) precision (here:  $d_{\text{in-situ}} = 457.1\text{nm}$ ;  $d_{\text{XRD}} = 458.8\text{nm}$ )
- The scatter in XRD growth rates, e.g. for GaAs layers in the same stack, is larger ( $\pm 0.6\%$ ) ! ... due to correlation effects in multi-layer analysis?

## Summary:

- **AlGaAs** → We have demonstrated:  
***in-situ* determination of**  
**x(0%....100%) with  $\pm 0.5\%$  precision** (formerly: 2% ... 3%)  
**growth rate r with  $\pm 0.3\%$  precision** (formerly: 1% ... 3%)

## Outlook #1:

- we will continue with AlGaInP (e.g. 650 nm)  
... by combining strain balancing  
(in-situ wafer bow meas.)  
with high-accuracy  
reflectance analysis. →



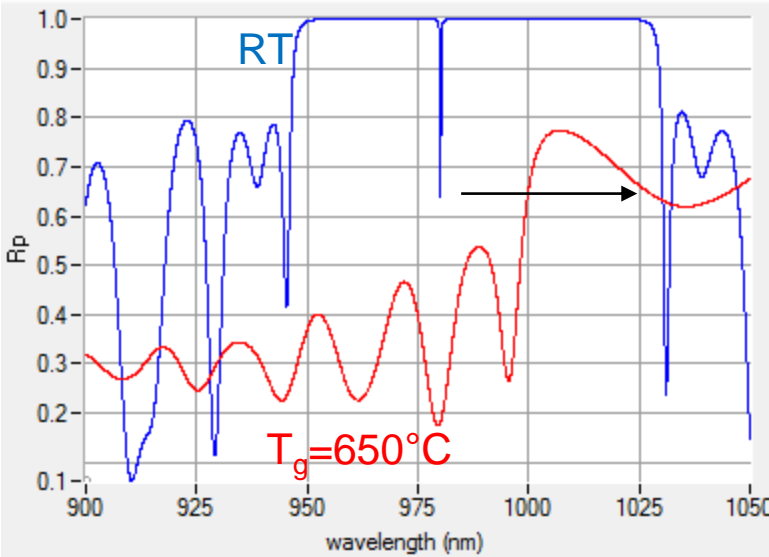
# Outlook #2: VCSEL process SPC

Example: 980nm InGaAs/AlGaAs VCSEL (x=12%/90% DBRs)

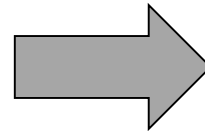
based on A.Mutig, PhD thesis, TU Berlin, 2010



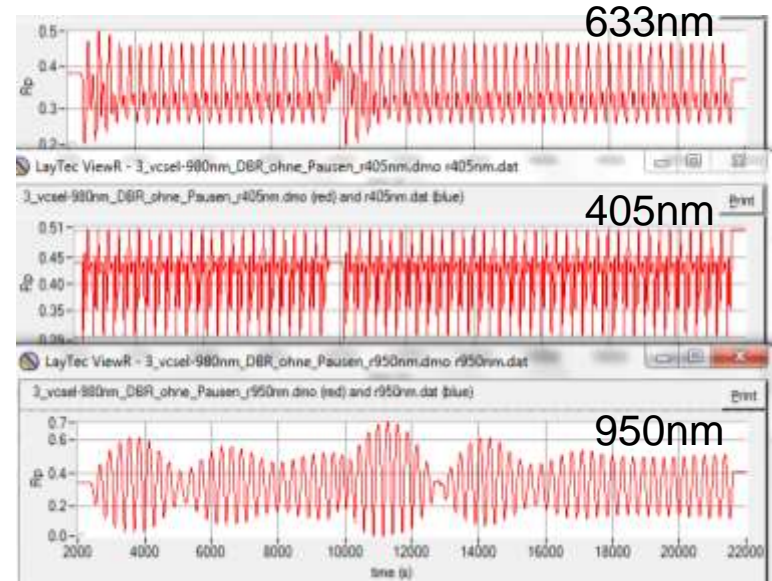
R spectrum: at  $T_g$  shifted to longer wavelength!



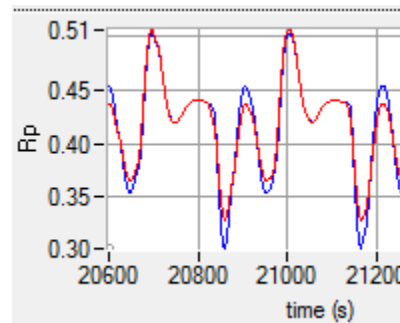
~5 hours  
MOCVD!



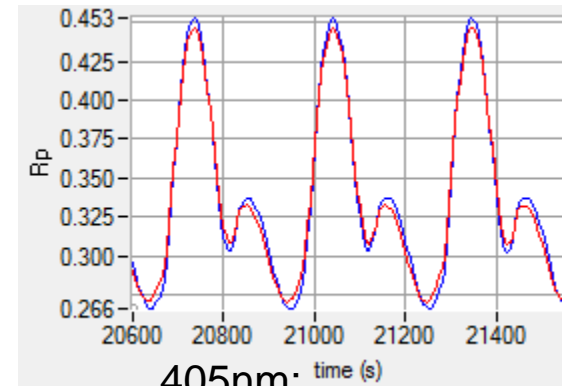
in-situ  
reflectance  
(simulated)



**New AlGaAs nk-database:** used for simulating 650°C in-situ data → intended (grading) and non-intended (r-drifting) VCSEL process changes show-up clearly and characteristically → **to be fed into SPC/MES!**



633nm:  
2% growth rate drift



405nm:  
Interface grading

The JENOPTIK logo, consisting of a white curved line above the word "JENOPTIK" in white, bold, sans-serif capital letters, all contained within a blue square.

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